

2016 32nd Thermal Measurement, Modeling & Management Symposium (SEMI-THERM 2016)

**San Jose, California, USA
14-17 March 2016**



**IEEE Catalog Number: CFP16SEM-POD
ISBN: 978-1-5090-2337-0**

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IEEE Catalog Number:	CFP16SEM-POD
ISBN (Print-On-Demand):	978-1-5090-2337-0
ISBN (Online):	978-1-5090-2336-3
ISSN:	1065-2221

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As you further develop a technique or application, consider documenting it for the thermal community. **SEMI-THERM 33** will begin accepting abstracts during the summer (deadline is September 15, 2016). We welcome your submissions! Visit us at www.semi-therm.org.